



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2014-10-03
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Giovanni Giacopello	Representative Title	AMS & IPD Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	TODP*ED6BB6F	A	Z8GA	2014-10-03
Amount	UoM	Unit type	ST ECOPACK Grade	
355.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Tin (Sn), matte	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
SIP	6.5,6.1,2.3	3	gull wing	
Comment	Package: TO 252 DPAK; MDF valid for STD16NF06T4			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	false
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-16th June 2014				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	TODP*ED6886F					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Silicon Die	Other inorganic materials	2.249	mg	supplier	die	Silicon (Si)	7440-21-3		2.168	mg	963984	6107
Silicon Die				supplier	metallization	Aluminium (Al)	7429-90-5		0.042	mg	18675	118
Silicon Die				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.02	mg	8893	56
Silicon Die				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.001	mg	445	3
Silicon Die				supplier	back side metallization	Gold (Au)	7440-57-5		0.003	mg	1334	8
Silicon Die				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.015	mg	6670	42
Leadframe	Copper & its alloys	200.349	mg	supplier	alloy	Copper(CU)	7440-50-8		199.993	mg	998223	563361
Leadframe				supplier	alloy	Tin(Sn)	7440-31-5		0.24	mg	1198	676
Leadframe				supplier	alloy	Nickel	7440-02-0		0.116	mg	579	327
Soft solder	Solder	2.009	mg	supplier	solder	Tin(Sn)	7440-31-5		0.04	mg	19910	113
Soft solder				supplier	solder	Silver(Ag)	7440-22-4		0.05	mg	24888	141
Soft solder				supplier	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	1.919	mg	955202	5406
Bonding wire	Other inorganic materials	0.973	mg	supplier	wire	Aluminium(Al)	84195-93-7		0.973	mg	1000000	2741
Encapsulation	Other Organic Materials	146.346	mg	supplier	mold compound	Silica Fused	60676-86-0		107.39	mg	733809	302507
Encapsulation				supplier	mold compound	Silica amorphous	7631-86-9		14.7	mg	100447	41408
Encapsulation				supplier	mold compound	Epoxy resin	proprietary		14.7	mg	100447	41408
Encapsulation				supplier	mold compound	Phenolic resin	proprietary		8.82	mg	60268	24845
Encapsulation				supplier	mold compound	Carbon Black	1333-86-4		0.736	mg	5029	2073
Finishing	Solder	3.074	mg	supplier	solder alloy	Tin(Sn)	7440-31-5		3.074	mg	1000000	8659